

1 Mbps HIGH CMR ANALOG OUTPUT TYPE  
5-PIN SOP PHOTOCOUPLER

–NEPOC Series–

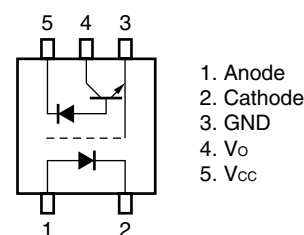
## DESCRIPTION

The PS8101 is an optically coupled isolator containing a GaAlAs LED on the light emitting diode (input side) and a PIN photodiode and a high-speed amplifier transistor on the output side on one chip.

This is a plastic SOP (Small Out-line Package) type for high density applications.

## FEATURES

- High common mode transient immunity ( $C_{MH}$ ,  $C_{ML} = \pm 10 \text{ kV}/\mu\text{s MIN.}$ )
- ★ • Small package (5-pin SOP)
- High supply voltage ( $V_{CC} = 35 \text{ V}$ )
- High isolation voltage ( $BV = 2\,500 \text{ Vr.m.s.}$ )
- High-speed response ( $t_{PHL} = 0.8 \mu\text{s MAX.}$ ,  $t_{PLH} = 1.2 \mu\text{s MAX.}$ )
- Ordering number of taping product: PS8101-F3, F4: 2 500 pcs/reel
- ★ • Pb-Free product
- ★ • Safety standards
  - UL approved: File No. E72422
  - DIN EN60747-5-2 (VDE0884 Part2) approved: No. 40008902 (Option)

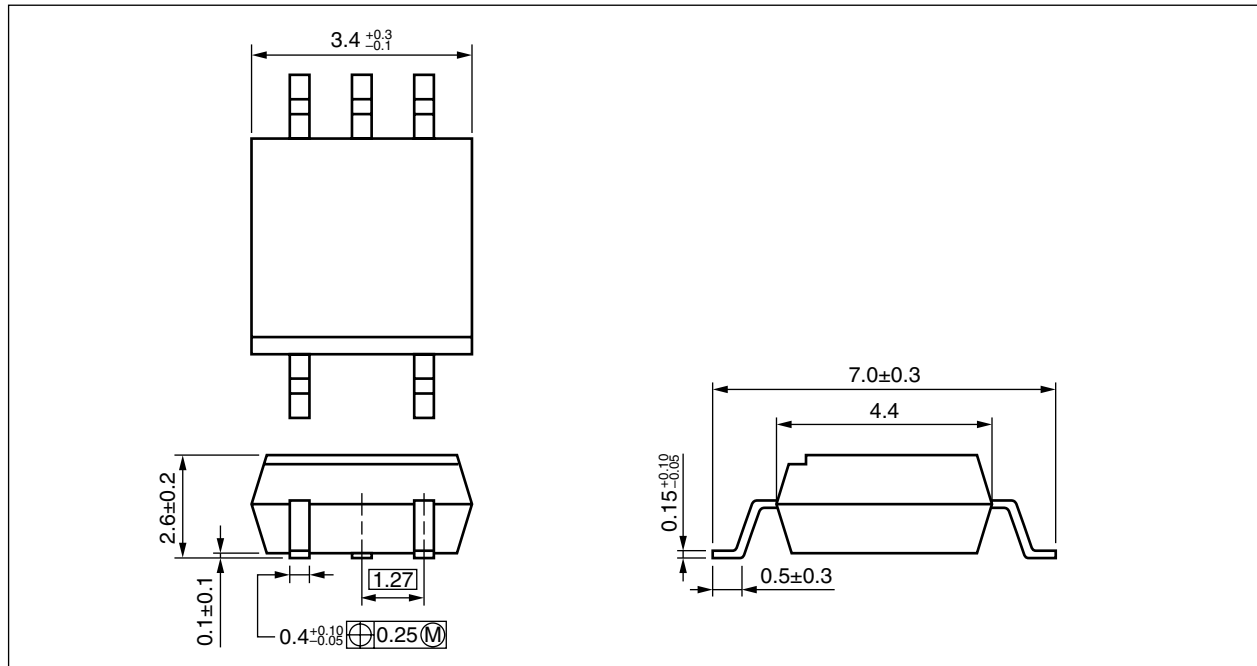
PIN CONNECTION  
(Top View)

## APPLICATIONS

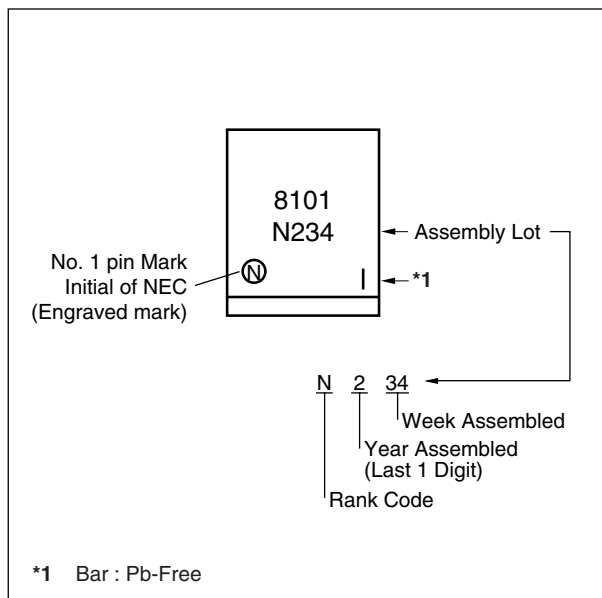
- Computer and peripheral manufactures
- General purpose inverter
- Substitutions for relays and pulse transformers
- Power supply

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PACKAGE DIMENSIONS (UNIT: mm)



★ MARKING EXAMPLE



★ ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number <sup>1</sup>
PS8101	PS8101-A	Pb-Free <sup>2</sup>	Magazine case 100 pcs	Standard products (UL approved)	PS8101
PS8101-F3	PS8101-F3-A		Embossed Tape 2 500 pcs/reel		
PS8101-F4	PS8101-F4-A				
PS8101-V	PS8101-V-A		Magazine case 100 pcs	DIN EN60747-5-2 (VDE0884 Part2) Approved (Option)	
PS8101-V-F3	PS8101-V-F3-A		Embossed Tape 2 500 pcs/reel		
PS8101-V-F4	PS8101-V-F4-A				

\*1 For the application of the Safety Standard, following part number should be used.

\*2 With regards to terminal solder (the solder contains lead) plated products (conventionally plated), contact your nearby sales office.

**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25°C, unless otherwise specified)**

Parameter		Symbol	Ratings	Unit
Diode	Forward Current	I <sub>F</sub>	25	mA
	Reverse Voltage	V <sub>R</sub>	5.0	V
	Power Dissipation <sup>*1</sup>	P <sub>D</sub>	45	mW
Detector	Supply Voltage	V <sub>CC</sub>	35	V
	Output Voltage	V <sub>O</sub>	35	V
	Output Current	I <sub>O</sub>	8.0	mA
	Power Dissipation <sup>*2</sup>	P <sub>C</sub>	100	mW
Isolation Voltage <sup>*3</sup>		BV	2 500	Vr.m.s.
Operating Ambient Temperature		T <sub>A</sub>	−55 to +100	°C
Storage Temperature		T <sub>stg</sub>	−55 to +125	°C

\*1 Reduced to 0.45 mW/°C at T<sub>A</sub> = 25°C or more.

\*2 Reduced to 1.00 mW/°C at T<sub>A</sub> = 25°C or more.

\*3 AC voltage for 1 minute at T<sub>A</sub> = 25°C, RH = 60 % between input and output.  
Pins 1-2 shorted together, 3-4 shorted together.

**ELECTRICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C)**

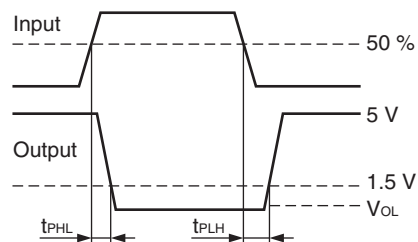
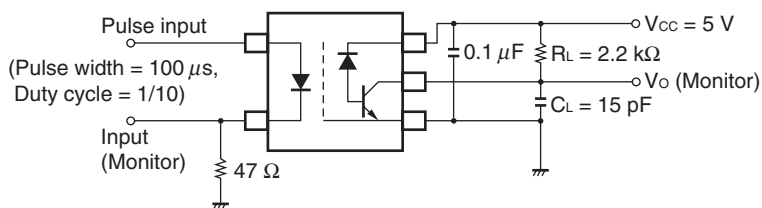
Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 16 mA		1.7	2.2	V
	Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 3 V			10	μA
	Forward Voltage Temperature Coefficient	ΔV <sub>F</sub> /ΔT	I <sub>F</sub> = 16 mA		-2.1		mV/°C
	Terminal Capacitance	C <sub>t</sub>	V = 0 V, f = 1 MHz		30		pF
Detector	High Level Output Current	I <sub>OH</sub> (1)	I <sub>F</sub> = 0 mA, V <sub>CC</sub> = V <sub>O</sub> = 5.5 V		3	500	nA
	High Level Output Current	I <sub>OH</sub> (2)	I <sub>F</sub> = 0 mA, V <sub>CC</sub> = V <sub>O</sub> = 30 V			100	μA
	Low Level Output Voltage	V <sub>OL</sub>	I <sub>F</sub> = 16 mA, V <sub>CC</sub> = 4.5 V, I <sub>O</sub> = 1.2 mA		0.1	0.4	V
	Low Level Supply Current	I <sub>CC</sub> L	I <sub>F</sub> = 16 mA, V <sub>O</sub> = open, V <sub>CC</sub> = 30 V		50		μA
	High Level Supply Current	I <sub>CC</sub> H	I <sub>F</sub> = 0 mA, V <sub>O</sub> = open, V <sub>CC</sub> = 30 V		0.01	2	
Coupled	Current Transfer Ratio <sup>*1</sup>	CTR	I <sub>F</sub> = 16 mA, V <sub>CC</sub> = 4.5 V, V <sub>O</sub> = 0.4 V	15	20	35	%
	Isolation Resistance	R <sub>I-O</sub>	V <sub>I-O</sub> = 1 kV <sub>DC</sub> , RH = 40 to 60%	10 <sup>11</sup>			Ω
	Isolation Capacitance	C <sub>I-O</sub>	V = 0 V, f = 1 MHz		0.4		pF
	Propagation Delay Time (H → L) <sup>*2</sup>	t <sub>PHL</sub>	I <sub>F</sub> = 16 mA, V <sub>CC</sub> = 5 V, R <sub>L</sub> = 2.2 kΩ, C <sub>L</sub> = 15 pF		0.5	0.8	μs
	Propagation Delay Time (L → H) <sup>*2</sup>	t <sub>PLH</sub>			0.6	1.2	
	Common Mode Transient Immunity at High Level Output <sup>*3</sup>	C <sub>MH</sub>	I <sub>F</sub> = 0 mA, V <sub>CC</sub> = 5 V, R <sub>L</sub> = 4.1 kΩ, V <sub>CM</sub> = 1.5 kV	10			kV/μs
	Common Mode Transient Immunity at Low Level Output <sup>*3</sup>	C <sub>ML</sub>	I <sub>F</sub> = 16 mA, V <sub>CC</sub> = 5 V, R <sub>L</sub> = 4.1 kΩ, V <sub>CM</sub> = 1.5 kV	-10			

\*1 CTR rank

K : 20 to 35 (%)

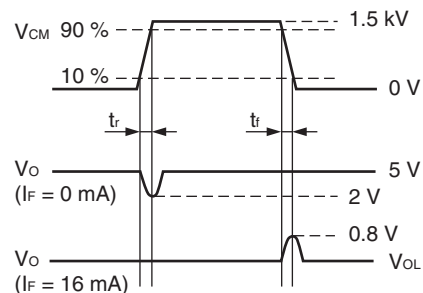
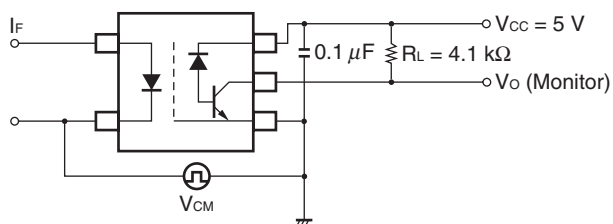
N : 15 to 35 (%)

**\*2 Test circuit for propagation delay time**



$C_L$  is approximately 15 pF which includes probe and stray wiring capacitance

**\*3 Test circuit for common mode transient immunity**

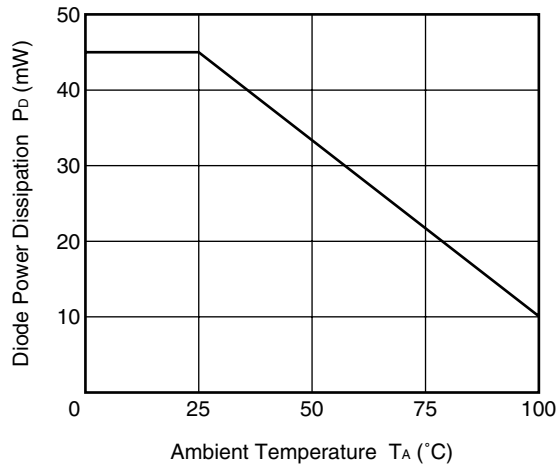


**USAGE CAUTIONS**

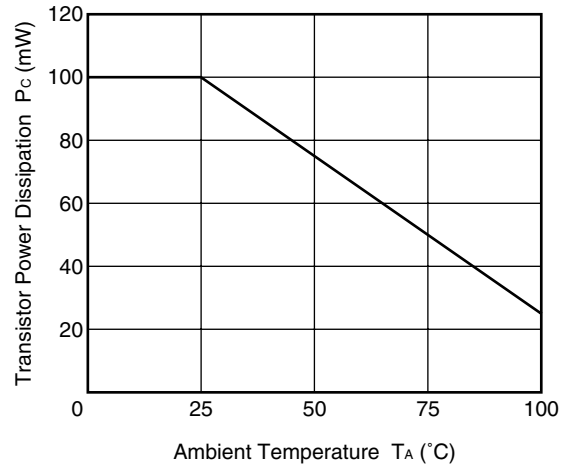
1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
2. By-pass capacitor of 0.1  $\mu$ F is used between  $V_{CC}$  and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
3. Avoid storage at a high temperature and high humidity.

**TYPICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ , unless otherwise specified)**

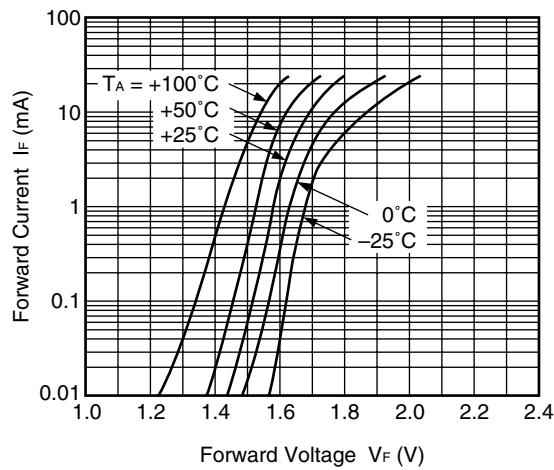
**DIODE POWER DISSIPATION vs. AMBIENT TEMPERATURE**



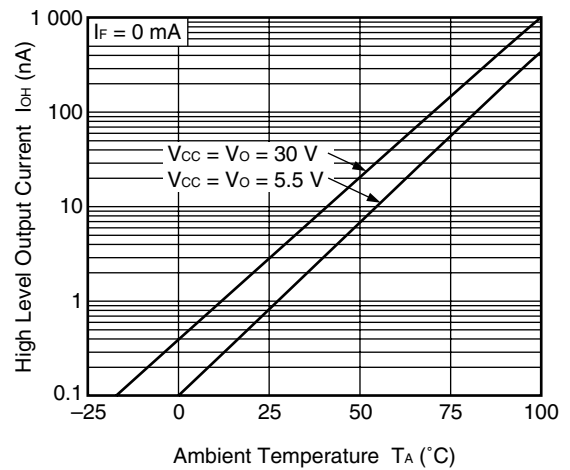
**TRANSISTOR POWER DISSIPATION vs. AMBIENT TEMPERATURE**



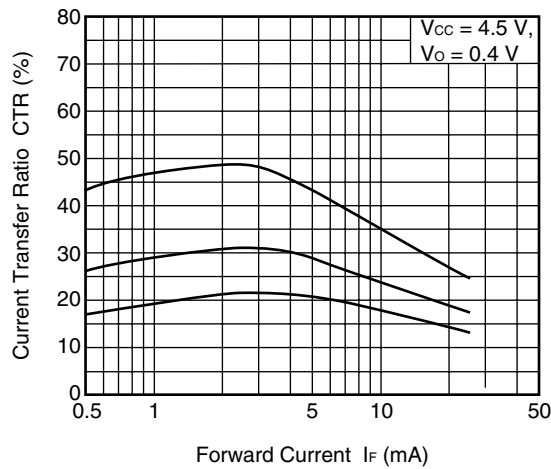
**FORWARD CURRENT vs. FORWARD VOLTAGE**



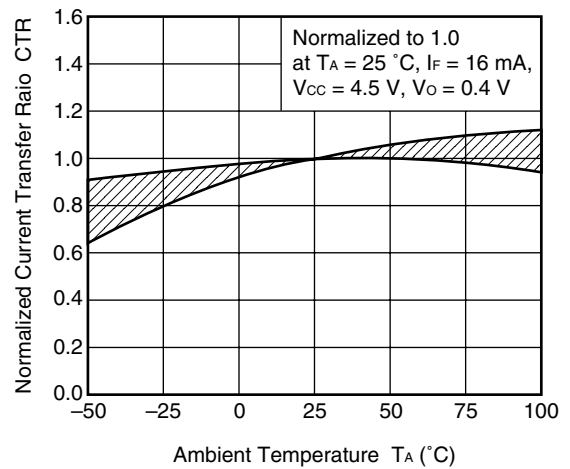
**HIGH LEVEL OUTPUT CURRENT vs. AMBIENT TEMPERATURE**



**CURRENT TRANSFER RATIO vs. FORWARD CURRENT**

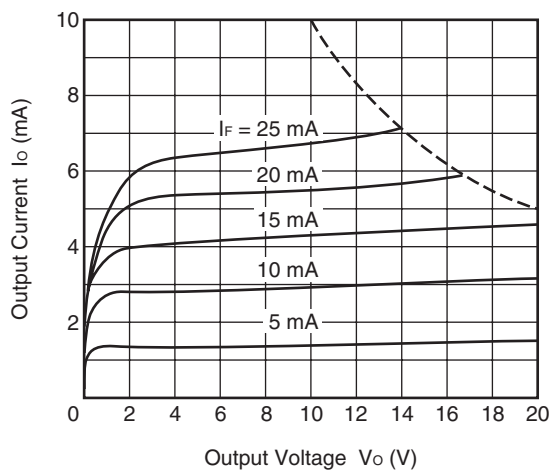


**NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE**

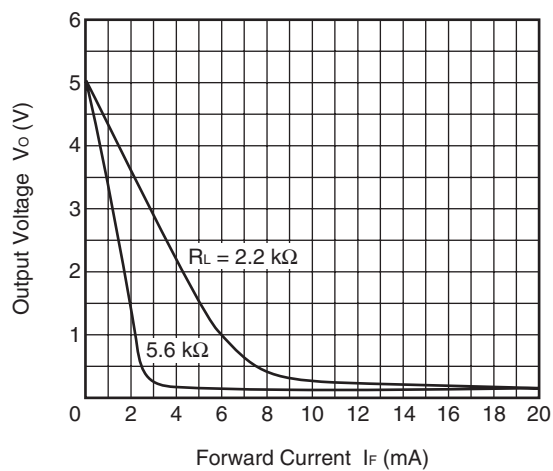


**Remark** The graphs indicate nominal characteristics.

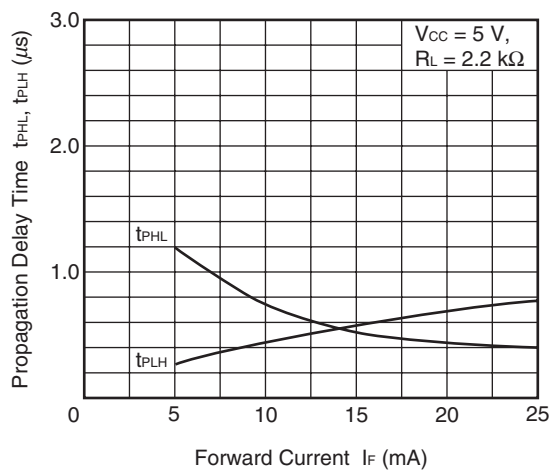
OUTPUT CURRENT vs.  
OUTPUT VOLTAGE



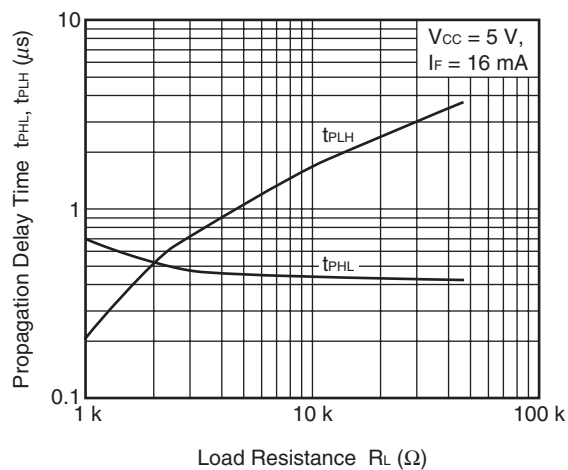
OUTPUT VOLTAGE vs.  
FORWARD CURRENT



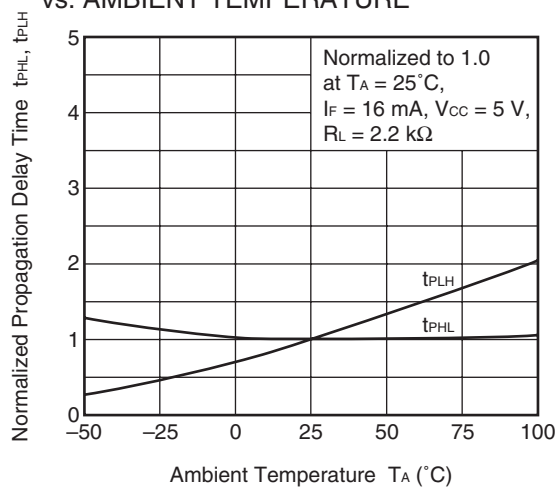
PROPAGATION DELAY TIME vs.  
FORWARD CURRENT



PROPAGATION DELAY TIME vs.  
LOAD RESISTANCE



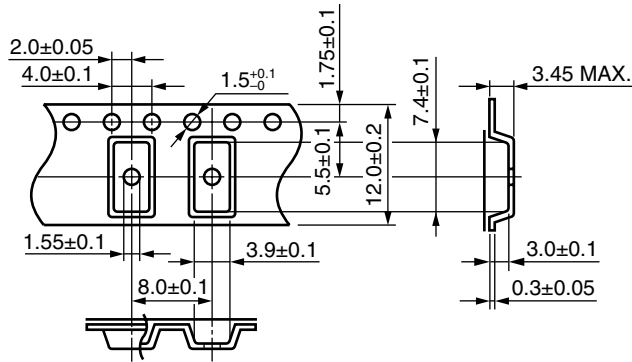
NORMALIZED PROPAGATION DELAY TIME  
vs. AMBIENT TEMPERATURE



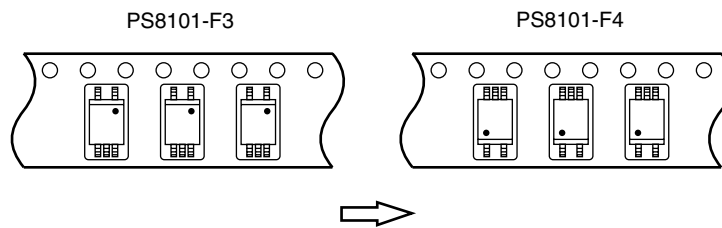
**Remark** The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT: mm)

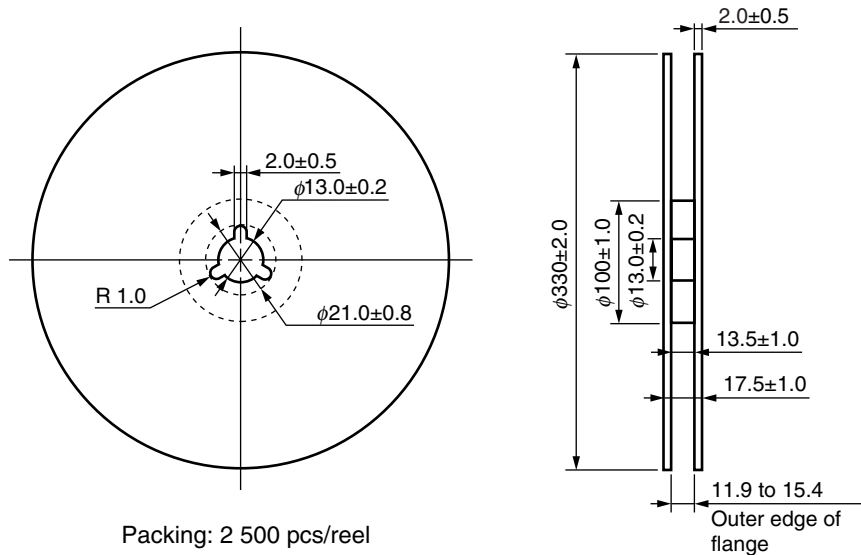
Outline and Dimensions (Tape)



Taping Direction



Outline and Dimensions (Reel)





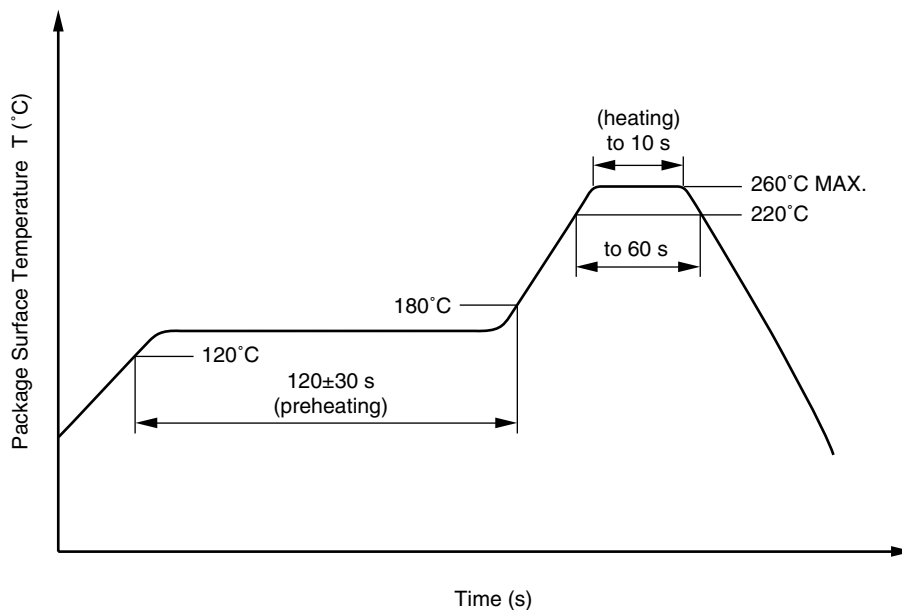
## NOTES ON HANDLING

### 1. Recommended soldering conditions

#### (1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



#### (2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

#### ★ (3) Soldering by Soldering Iron

- Peak Temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead

(b) Please be sure that the temperature of the package would not be heated over 100°C

**(4) Cautions**

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

**2. Cautions regarding noise**

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

**★ USAGE CAUTIONS**

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

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M8E 00.4-0110

<div data-bbox="162 210 284 280"> <b>Caution</b> </div> <div data-bbox="300 241 459 280"> GaAs Products </div>	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> <li>• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. <ol style="list-style-type: none"> <li>1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.</li> <li>2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.</li> </ol> </li> <li>• Do not burn, destroy, cut, crush, or chemically dissolve the product.</li> <li>• Do not lick the product or in any way allow it to enter the mouth.</li> </ul>
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►For further information, please contact

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